

METHOD FOR MANUFACTURING MULTILAYER WIRING BOARD

ABSTRACT

5 A method for manufacturing a multilayer wiring board, comprising: a step (I) of preparing a plurality of printed wiring boards having both electrical connection pads for establishing an electrical connection between the printed wiring boards and non-connection pads for not establishing an electrical connection between the printed wiring
10 boards on the same plane; and a lamination step (II) of overlaying the plurality of printed wiring boards so that the electrical connection pads face each other, and laminating the plurality of printed wiring boards so that the printed wiring boards are bonded to each other through a conductive material provided between the facing electrical connection
15 pads. In the printed wiring board manufacturing step (I), to at least one of surfaces faced when the plurality of printed wiring boards are overlaid in the lamination step (II), an insulating film having through holes formed in positions corresponding to the electrical connection pads on the surface is attached (Ia), and the conductive material is
20 provided in the through holes formed in the insulating film (Ib).

Fig. 1